



*Focus on Quality*

ISIS  
sentronics

## SemDex<sup>®</sup>295

### Cost-effective Table-top System for Bow/Warp and Thickness Evaluation



The **SemDex 295** device was designed for off-line applications in quality assurance. This compact table-top device is fitted with a sensor and with a motorized rotary table and integrated x-stage for fast non-contact measurement of wafers up to 300 mm (12").

Substrate layer thickness and bow/warp of the object can be determined with (sub-)  $\mu\text{m}$  accuracy accuracy in a single scan.

Intuitive **WaferSpect** software facilitates measurement planning by means of protocols, execution of the measuring tasks, saving of the relevant measurement data, and their processing, presentation, and export.

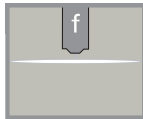
#### Optical Metrology:

- (Substrate) thicknesses with sub- $\mu\text{m}$  accuracy
- Bow/warp, flatness with  $\mu\text{m}$  accuracy

#### Features:

- Easy manual loading
- Fast automatic measurement
- Thickness and Bow/ Warp measurement in one step
- Compact device with optimal footprint
- High data acquisition through rotational stage
- User-friendly software

## Integrated Sensor: StraDex f



### SemDex 295-11

- Substrate thickness
- Bow / Warp

## Specifications SemDex 295:

Accuracy after pattern recognition	5 µm (as option)
SECS/ GEM capability	yes (as option)
Max. number of metrology sensors	1
Dimensions	560 x 520 x 550 mm <sup>3</sup>

Layer thickness sensor 1 / 2	StraDex f24 - 300	StraDex f2 - 80
Thickness range (silicon)	8 - 800 µm*	2.5 - 60 µm
Spot size	24 µm	8 µm
Wavelength	1300 nm	830 nm
Working range	24 - 44 mm	2 - 22 mm
Repeatability		0.1 µm
Field-of-view of integrated camera		ca. 3 x 3 mm <sup>2</sup>

\* You can also use StraDex f2 - 300 for measuring layer thicknesses < 200 µm

We are members of:

